



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/004,172
Filing Date October 9, 2001
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner Unassigned
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and
Bonding Frames

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References –See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449, copies of which are attached. No admission is made regarding whether all the submitted references are prior art.

Citation of the referenced art is respectfully requested.

This Supplemental Information Disclosure Statement is being filed within three months of the filing date of the application or before the mailing date of a first Office Action, whichever occurs last. Therefore, no fee is believed to be required. However, in the event that a fee is required for filing this Supplemental Information Disclosure Statement, please charge the fee specified under 37 C.F.R. § 1.17(p) to Deposit Account No. 23-0925.

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Respectfully submitted,

TECHNOLOGY CENTER R3701

Dated: _____

11/20/02

By: _____

James D. Shaurette
Reg. No. 39,833



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Respectfully submitted,

TECHNOLOGY CENTER R3700

Dated: Aug. 23, 2002

By:

Frederick M. Fliegel, Ph.D.
Reg. No. 36,138



EL 844051657

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/148,723
Priority Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Priority Group Art Unit 3729
Priority Examiner A. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

INFORMATION DISCLOSURE STATEMENT

References - - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a divisional application of co-pending Application Serial No. 09/148,723, filed September 3, 1998, upon which the above-identified application relies for a priority dated under 35 U.S.C. §120. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2). As a courtesy, Applicant submits copies of the cited article and foreign references for review.


Citation of these references is respectfully requested.

Respectfully submitted,

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Date: Oct 8, 2001



Frederick M. Fliegel, Ph.D.
Reg. No. 36,138

TECHNOLOGY CENTER R3700



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/004,172
Filing Date October 9, 2001
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and
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References -See Attached Form PTO-1449

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Citation of the referenced art is respectfully requested.

Respectfully submitted,

Dated: 4-10-03

By: 
D. Brent Kenady
Reg. No. 40,045

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